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, L	To the Director of the U.S	. Patent and Tradem	nark Office.	, 10030 100010 tilo attacilou t	JUCUIIIOIII.	
1.	Name of conveying (1) Jin Mun RYU (2) Jung Jin KIM (3) Hyung Kyu PA					
<b>2</b> .	Name and Address SAMSUNG ELECT 314 Maetan 3-Don Suwon, Gyunggi-D Republic of Korea	TRO-MECHÂNI g, Yeongtong-C	ICS CO., I	LTD.		•
3.	Nature of conveya	nce:			•	•
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	Execution Date(s):	(1), (2), (3), Ju	ıly 16, 200	<u>07</u>		
4.	OR	is being filed to	ogether w	ith a new application. of the application:		
		lication No(s). , s). , issued .	filed; or			
5.	Name and address STAAS & HALSEY Attention: <u>David M</u> 1201 New York Av Washington, D.C.	LLP I. Pitcher e., N.W., Suite		pondence concerning Our Docket:		
6.	Total number of applications and patents involved:1					
7.	Total fee (37 CFR 3.41) (\$ 40.00 per Patent or Application in Assignment)  ⊠ Enclosed  □ Authorized to be charged to deposit account.					
8.	Account)	•	•	rpayment is authorize		
	M. Pitcher, Reg. No of Person Signing	<u>. 25,908</u>	As s	19/01 24 FC audition		EN2 00000052 11905314 48.00
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**PATENT** 

**REEL: 019959 FRAME: 0942** 

Docket No.

S&H 7403

## **U.S. ASSIGNMENT**

IN CONSIDERATION of the sum of One Dollar ( inventor(s) (hereinafter, "ASSIGNOR") by	\$1.00), and of other good and	d valuable consideration paid to the undersigned
(Insert Name(s) & Address(es) of ASSIGNEE(S))		
SAMSUNG Electro-Mechanics Co., Ltd.		
314 Maetan 3-Dong, Yeongtong-Gu.		
Suwon, Gyunggi-Do		
Republic of KOREA		
(hereinafter, "ASSIGNEE"), the receipt of which is heret ASSIGNEE the entire and exclusive right, title and intere (Title of Invention)		ed ASSIGNOR hereby sells, assigns and transfers to
WAFER LEVEL CHIP SCALE PACKAGE O	F IMAGE SENSOR AND	MANUFACTURING METHOD THEREOF
relating to International Patent Application PCT//_executed on even date herewith or, if not so executed, wa		ication for Letters Patent of the United States was
(a) executed on	; (Insert date of execution	on of application, if not concurrent)
(b) filed on;	N.W., Suite 700, Wash	y of STAAS & HALSEY ILP, 1201 New York Ave., Ington, D.C. 20005 (202/434-1500) is hereby (b) the specified data, when known.
and to said application and all Letters Patent(s) of the Unit eissue or reexamination application based thereon, for the my extensions thereof (collectively, hereinafter, "said app The ASSIGNOR agree(s), when requested by said ASS	e full term or terms for which the plication(s) and Letters Putent(s)	e said Letters Patent(s) may be granted and including (*).
which the ASSIGNEE may deem necessary, desirable or oncluding in the preparation and prosecution of said applic occamination, or public use proceeding, and in any litigations to include but not be limited to executing all papers, it was testimony, and obtaining and producing evidence.	expedient, for securing, maintain cation(s) and the issuance of said tion or other legal proceeding wi	ning and enforcing protection for said invention,  I Letters Patent(s), in any interference, reissue, nich may arise or be declared in relation to same, such
IN WITNESS WHEREOF, the undersigned inventor(s (Typed Name & Signature of Inventor(s))	) has (have) affixed his/her/their (Dats)	signature(s). (Typed Name & Signature of Witness(es))
) <i>I</i>	2009/1/16	
RYU Jin Mun	2007/1/16	
KIM Jung Jin	2001/7/16	

PATENT REEL: 019959 FRAME: 0943

**RECORDED: 09/28/2007**